

# 2SC5658 / 2SC4617EB / 2SC4617 2SC4081UB / 2SC4081U3 / 2SC2412K

General purpose small signal amplifier (50V, 150mA)

Datasheet

Parameter	Value
V <sub>CEO</sub>	50V
I <sub>C</sub>	150mA

#### Features

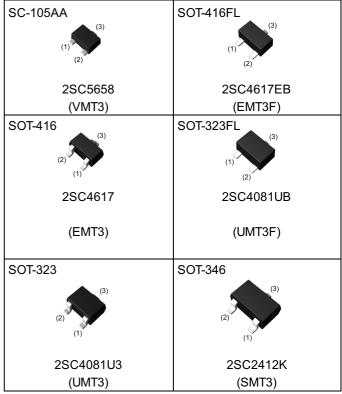
1)Low Cob.Cob=2.0pF(Typ.)

2)Complements the 2SA2029/ 2SA1774EB/2SA1774/2SA1576UB/ 2SA1576U3/2SA1037AK.

#### Application

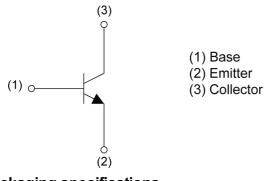
GENERAL PURPOSE SMALL SIGNAL AMPLIFIER

## Outline

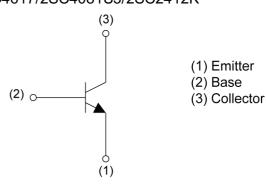


#### •Inner circuit

2SC5658/2SC4617EB/2SC4081UB



## 2SC4617/2SC4081U3/2SC2412K



## Packaging specifications

- : ackaging of								
Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Quantity (pcs)	hFE rank	Marking
2SC5658	SC-105AA	1212	T2L	180	8	8000	QR	В
2SC4617EB	SOT-416FL	1616	TL	180	8	3000	QR	В
2SC4617	SOT-416	1616	TL	180	8	3000	QR	В
2SC4081UB	SOT-323FL	2021	TL	180	8	3000	QR	В
2SC4081U3	SOT-323	2021	T106	180	8	3000	QR	В
2SC2412K	SOT-346	2928	T146	180	8	3000	QR	В

## ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

F	Parameter	Symbol	Values	Unit
Collector-base voltage		V <sub>CBO</sub>	60	V
Collector-emitter voltage		V <sub>CEO</sub>	50	V
Emitter-base voltage		V <sub>EBO</sub>	7	V
Callagton augment		I <sub>C</sub>	150	mA
Collector current		I <sub>CP</sub> *1	200	mA
	2SC5658		150	
	2SC4617EB		150	
Davier dia sin etia e	2SC4617	D *2	150	\^/
Power dissipation	2SC4081UB	$P_D^{*2}$	200	mW
	2SC4081U3		200	
	2SC2412K		200	
Junction temperature	<u>.</u>	T <sub>j</sub>	150	°C
Range of storage tempera	ature	T <sub>stg</sub>	-55 to +150	°C

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumbal	Symbol Conditions		Values		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	BV <sub>CBO</sub>	I <sub>C</sub> = 50μA	60	-	-	V
Collector-emitter breakdown voltage	BV <sub>CEO</sub>	I <sub>C</sub> = 1mA	50	-	-	<b>V</b>
Emitter-base breakdown voltage	BV <sub>EBO</sub>	I <sub>E</sub> = 50μA	7	1	1	V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 60V	1	1	100	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = 7V	•	1	100	nA
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 50$ mA, $I_B = 5$ mA	•	•	400	mV
DC current gain	h <sub>FE</sub>	$V_{CE} = 6V$ , $I_{C} = 1mA$	120	1	390	-
Transition frequency	f <sub>T</sub>	$V_{CE} = 12V, I_{E} = -2mA,$ f = 100MHz	-	180	-	MHz
Output capacitance	C <sub>ob</sub>	$V_{CB} = 12V$ , $I_E = 0A$ , $f = 1MHz$	-	2.0	3.5	pF

## hFE values are calssified as follows:

rank	Q	R	-	-	-
h <sub>FE</sub>	120-270	180-390	-	-	-

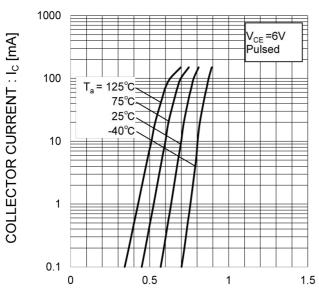
<sup>\*1</sup> Pw=1ms, Single Pulse.



<sup>\*2</sup> Each terminal mounted on a reference land.

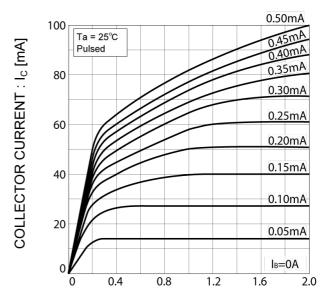
## ● Electrical characteristic curves(T<sub>a</sub> = 25°C)

Fig.1 Ground Emitter Propagation Characteristics



BASE TO EMITTER VOLTAGE :  $V_{\text{BE}}\left[V\right]$ 

Fig.2 Grounded Emitter Output Characteristics



COLLECTOR TO EMITTER VOLTAGE: V<sub>CE</sub> [V]

Fig.3 DC Current Gain vs. Collector Current (I)

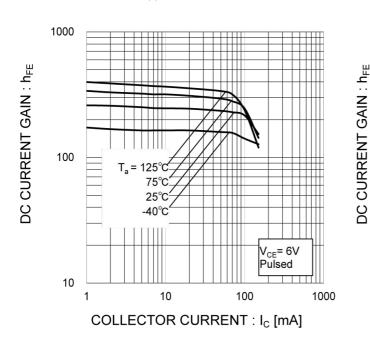
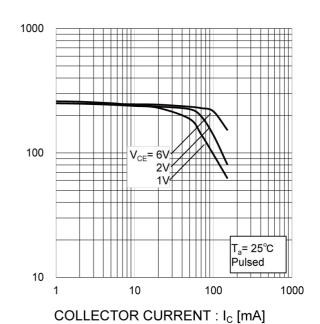


Fig.4 DC Current Gain vs. Collector Current (II)



## ● Electrical characteristic curves(T<sub>a</sub> = 25°C)

Fig.5 Collector-Emitter Saturation Voltage vs. Collector Current(I)

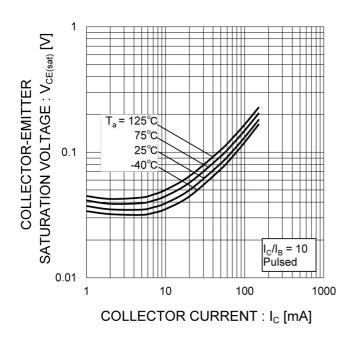


Fig.6 Collector-Emitter Saturation Voltage vs. Collector Current(II)

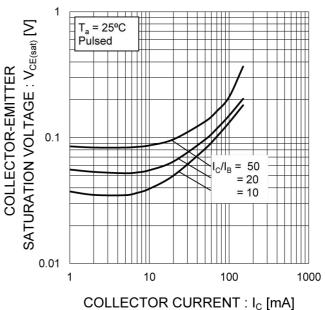


Fig.7 Base-Emitter Saturation Voltage vs. Collector Current (I)

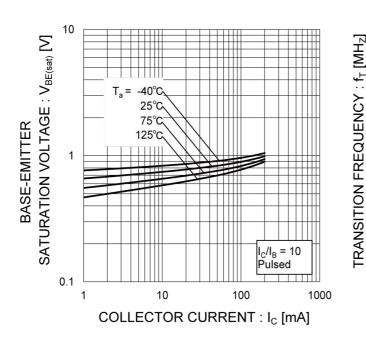
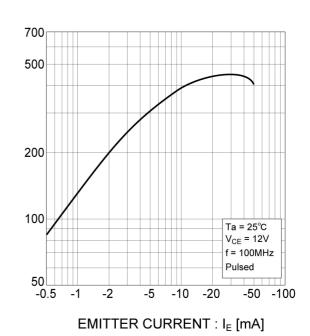


Fig.8 Gain Bandwith Product vs. Emitter Current



## ◆Electrical characteristic curves(T<sub>a</sub> = 25°C)

Fig.9 Collector Output Capacitance vs.
Collector-Base Voltage
Emitter Input Capacitance vs.
Emitter-Base Voltage

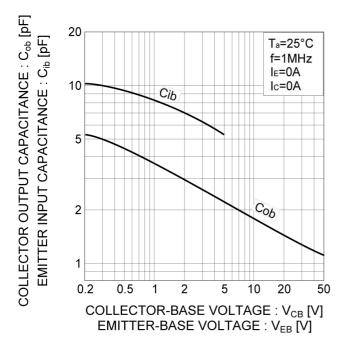


Fig.10 Safe Operating Area

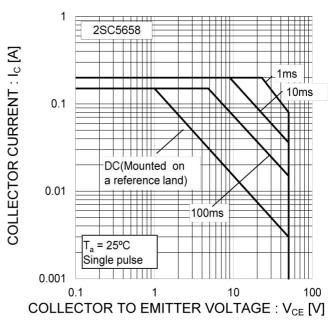


Fig.11 Safe Operating Area

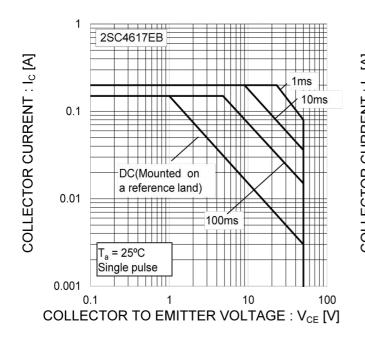
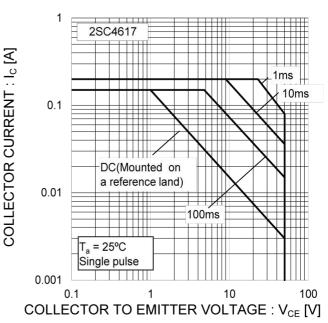


Fig.12 Safe Operating Area



## ● Electrical characteristic curves(Ta=25°C)

Fig.13 Safe Operating Area

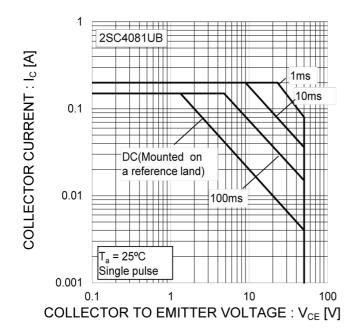


Fig.14 Safe Operating Area

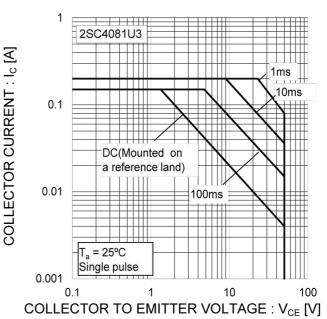
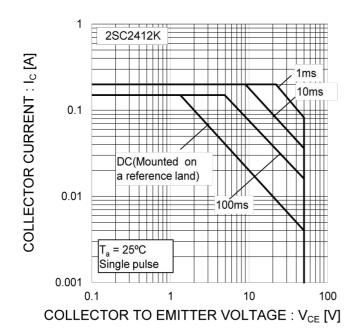
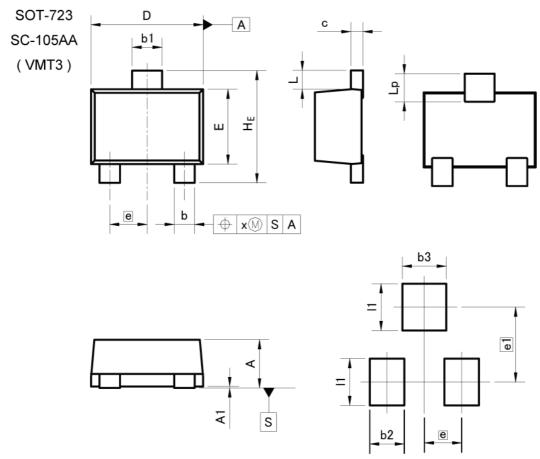


Fig.15 Safe Operating Area







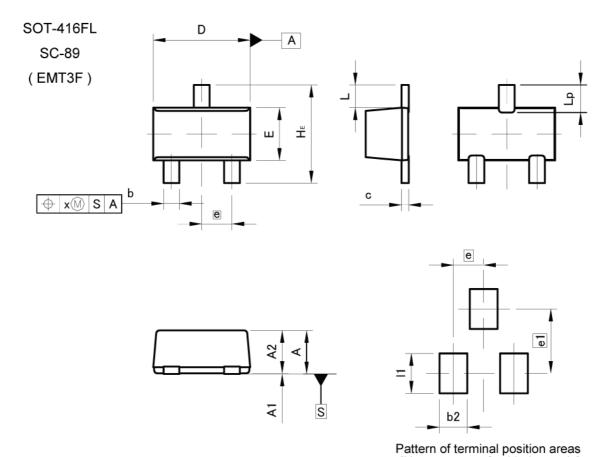
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
С	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
е	0.40		0.0	02
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
х	=	0.10	33	0.004

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	<del>11</del> 0	0.37	544	0.015
b3	226	0.47	822	0.019
e1	e1 0.80		0.0	031
11	<del>5</del> 8	0.50	200	0.020

Dimension in mm/inches





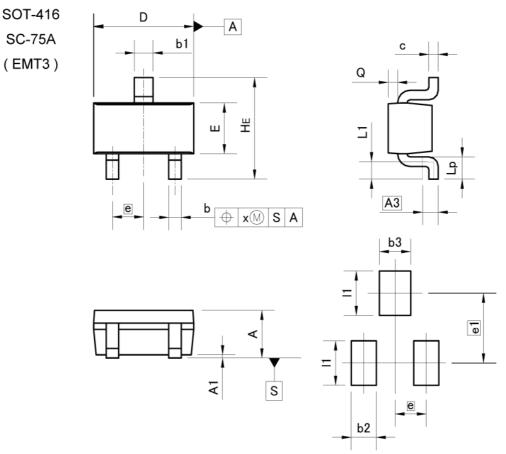
[Not a pattern of soldering pads]

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
Α	0.65	0.85	0.026	0.033
A1	0.00	0.10	0.000	0.004
A2	0.60	0.80	0.024	0.031
b	0.21	0.36	0.008	0.014
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	0.76	0.96	0.030	0.038
е	0.9	50	0.020	
HE	1.50	1.70	0.059	0.067
L	0.3	37	0.0	15
Lp	0.35	0.55	0.014	0.022
х		0.10	-	0.004

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	<del>=</del> 1	0.46	-	0.018
e1		1.05		0.041
- 11	=	0.65		0.026

Dimension in mm/inches





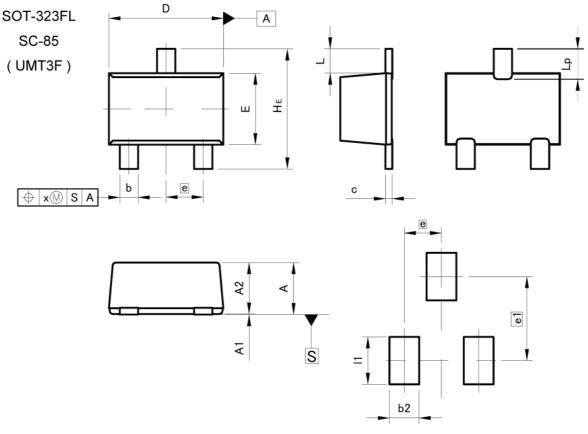
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
Α	0.60	0.80	0.024	0.031
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
е	0.	0.50 0.0		20
HE	1.40	1.80	0.055	0.071
L1	0.10	<u>≠</u> 3	0.004	8 <del>11</del>
Lp	0.15		0.006	255
Q	0.05	0.25	0.002	0.010
х	9.7	0.10		0.004

DIM	MILIM	MILIMETERS		HES
	MIN	MAX	MIN	MAX
b2	244	0.40	-	0.016
b3	10 <del>48</del>	0.50	; <del>; ; ; ; ; ; ; ; ; ; ; ; ; ; ; ; ; ; </del>	0.020
e1	1.	1.10		043
11		0.70	-	0.028

Dimension in mm/inches





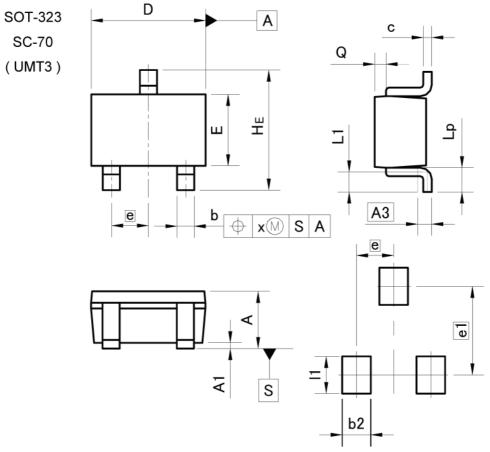
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
Α	0.85	1.05	0.033	0.041
A1	0.00	0.10	0.000	0.004
A2	0.80	1.00	0.031	0.039
b	0.27	0.42	0.011	0.017
С	0.08	0.18	0.003	0.007
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.0	65	0.0	26
HE	2.00	2.20	0.079	0.087
L	0.4	0.43		17
Lp	0.43	0.63	0.017	0.025
х	-	0.10		0.004

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
b2	<del>=</del> 8	0.52	-	0.020
e1	1.47		0.058	
11	-	0.83	-	0.033

Dimension in mm/inches





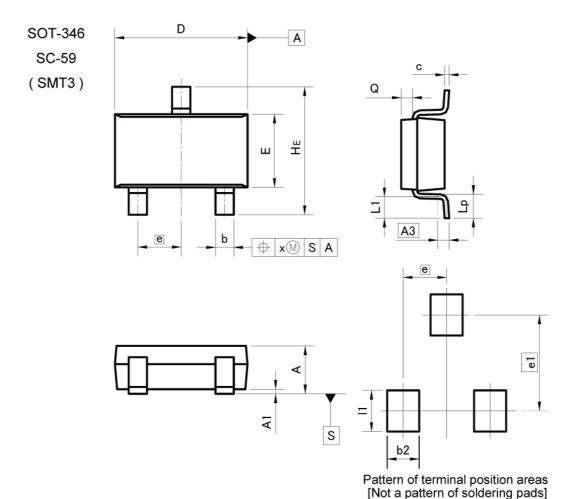
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	0.80	1.00	0.031	0.039	
A1	0.00	0.10	0	0.004	
A3	0.25		0.01		
b	0.25	0.40	0.01	0.016	
С	0.10	0.20	0.004	0.008	
D	1.90	2.10	0.075	0.083	
E	1.15	1.35	0.045	0.053	
е	0.65		0.03		
HE	2.00	2.20	0.079	0.087	
L1	0.20	0.50	0.008	0.02	
Lp	0.25	0.55	0.01	0.022	
Q	0.10	0.30	0.004	0.012	
х	_	0.10	_	0.004	

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
e1	1.55		0.06	
b2	<b>E</b>	0.50	<b>E</b>	0.02
11	_	0.65	_	0.026

Dimension in mm/inches





DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.010	
b	0.35	0.50	0.014	0.020
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-2	0.60	× <del>-</del>	0.024
e1	2.10		0.0	083
11	<b>-</b> 525	0.90	( <del>-</del>	0.035

0.10

0.10

Dimension in mm/inches

X



0.004

0.004

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Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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1 /			
JAPAN	USA	EU	CHINA
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CLASSIV		CLASSIII	CLASSIII

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  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### **Precaution for Mounting / Circuit board design**

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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